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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Packages, and Ceramic (J) DIPs

| 014111 | | P VI | • | |
|---|--|------|--|--|
| OE [1D [2D [3D [5D [7D [8D [6ND [| (TO 1 2 3 4 5 6 7 8 9 10 | | 20 19 18 17 16 15 14 13 12 11 | Vcc 10 20 30 40 50 70 80 CLK |
| | | | | |

SN54LVT574 ... J OR W PACKAGE

SN74LVT574 . . . DB. DW. OR PW PACKAGE

SN54LVT574 ... FK PACKAGE (TOP VIEW)

| | 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 | |
|----------------------------|---|----------------------------|
| | | |
| 3D 4D 5D 6D 7D | $\begin{bmatrix} 3 & 2 & 1 & 20 & 19 \\ 4 & & & 18 \\ 5 & & & 17 \\ 6 & & & 16 \\ 7 & & & 15 \\ 8 & & & 14 \\ 9 & 10 & 11 & 12 & 13 \\ \end{bmatrix}$ | 2Q 3Q 4Q 5Q 6Q |
| | CLK 20 BD 30 CLK | |

description

These octal flip-flops are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The eight flip-flops of the 'LVT574 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components. \overline{OE} does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT574 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVT574 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVT574 is characterized for operation from -40° C to 85° C.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

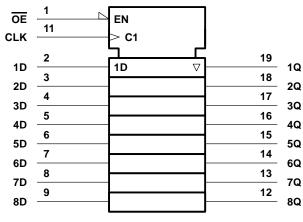


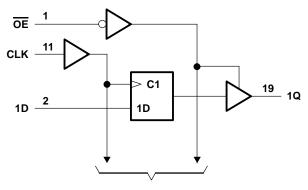
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| FUNCTION TABLE (each flip-flop) | | | | | | | | | |
|------------------------------------|------------|---|----------------|--|--|--|--|--|--|
| | OUTPUT | | | | | | | | |
| Ð | CLK | D | Q | | | | | | |
| L | \uparrow | Н | Н | | | | | | |
| L | \uparrow | L | L | | | | | | |
| L | H or L | Х | Q ₀ | | | | | | |
| Н | х | Х | Z | | | | | | |
| | | | | | | | | | |

logic symbol[†]





logic diagram (positive logic)

To Seven Other Channels

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

| Input voltage range, VI (see Note 1) $-0.5 V$ to 7 VVoltage range applied to any output in the high state or power-off state, VO (see Note 1) $-0.5 V$ to 7 VCurrent into any output in the low state, IO:SN54LVT57496 mASN74LVT574128 mACurrent into any output in the high state, IO (see Note 2):SN54LVT57448 mASN74LVT57464 mAInput clamp current, IIK (VI < 0) $-50 mA$ |
|--|
| Current into any output in the low state, I _O : SN54LVT574 96 mA SN74LVT574 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVT574 128 mA SN74LVT574 48 mA SN74LVT574 64 mA Input clamp current, I _{IK} (V _I < 0) |
| Current into any output in the low state, I _O : SN54LVT574 96 mA SN74LVT574 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVT574 128 mA SN74LVT574 48 mA SN74LVT574 64 mA Input clamp current, I _{IK} (V _I < 0) |
| SN74LVT574 128 mA Current into any output in the high state, I _O (see Note 2): SN54LVT574 48 mA SN74LVT574 64 mA Input clamp current, I _{IK} (V _I < 0) |
| SN74LVT574 |
| Input clamp current, I _{IK} (V _I < 0) |
| |
| |
| Output clamp current, I _{OK} (V _O < 0) |
| Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DB package |
| DW package 1.6 W |
| PW package |
| Storage temperature range, T _{stg} –65°C to 150°C |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



SN54LVT574, SN74LVT574 3.3-V ABT OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS SCBS139D - MAY 1992 - REVISED JULY 1995

recommended operating conditions (see Note 4)

| | | | SN54L | VT574 | SN74L | UNIT | |
|---------------------|------------------------------------|-----------------|-------|-------|-------|------|------|
| | | | MIN | MAX | MIN | MAX | UNIT |
| VCC | Supply voltage | | 2.7 | 3.6 | 2.7 | 3.6 | V |
| VIH | High-level input voltage | | 2 | | 2 | | V |
| VIL | Low-level input voltage | | 0.8 | | 0.8 | V | |
| VI | Input voltage | | | 5.5 | | 5.5 | V |
| ЮН | High-level output current | | | -24 | | -32 | mA |
| IOL | Low-level output current | | | 48 | | 64 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | Outputs enabled | | 10 | | 10 | ns/V |
| Т _А | Operating free-air temperature | | -55 | 125 | -40 | 85 | °C |

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| DADAMETER | TEST CONDITIONS | | | | 154LVT5 | 74 | SN | 74LVT5 | 74 | | |
|------------------|---|---|---------------------------------|--------------------|---------|------|--------------------|--------|------|------|--|
| PARAMETER | | FEST CONDITIONS | | MIN | TYP† | MAX | MIN | TYP† | MAX | UNIT | |
| VIK | V _{CC} = 2.7 V, | lj = –18 mA | | | | -1.2 | | | -1.2 | V | |
| | $V_{CC} = MIN \text{ to } MAX^{\ddagger}$ | , I _{OH} = –100 μA | | V _{CC} -0 |).2 | | V _{CC} -0 | .2 | | | |
| VOH | V _{CC} = 2.7 V, | I _{OH} = - 8 mA | | 2.4 | | | 2.4 | | | V | |
| | V _{CC} = 3 V | I _{OH} = - 24 mA | | 2 | | | | | | v | |
| | VCC = 3 V | $I_{OH} = -32 \text{ mA}$ | | | | | 2 | | | | |
| | V _{CC} = 2.7 V | I _{OL} = 100 μA | | | | 0.2 | | | 0.2 | | |
| | VCC = 2.7 V | I _{OL} = 24 mA | | | | 0.5 | | | 0.5 | | |
| Vo | | I _{OL} = 16 mA | | | | 0.4 | | | 0.4 | V | |
| VOL | $V_{CC} = 3 V$ | I _{OL} = 32 mA | 0.5 | | | 0.5 | | | v | | |
| | | I _{OL} = 48 mA | | | 0.55 | | | | | | |
| | | I _{OL} = 64 mA | | | | | | | 0.55 | | |
| ų | $V_{CC} = 0$ or MAX [‡] , | r MAX [‡] , V _I = 5.5 V | | | | 50 | | | 10 | | |
| | V _{CC} = 3.6 V | $V_I = V_{CC}$ or GND | Control inputs | | | ±1 | | | ±1 | μA | |
| | | VI = VCC | Data inputa | | | 1 | | | 1 | | |
| | | $V_{I} = 0$ | Data inputs | | | -5 | | | -5 | 1 | |
| l _{off} | $V_{CC} = 0,$ | V_{I} or V_{O} = 0 to 4.5 V | | | | | | | ±100 | μΑ | |
| 1.4 | V _{CC} = 3 V | V _I = 0.8 V | Data inputs | 75 | | | 75 | | | μA | |
| ll(hold) | VCC = 3 V | V _I = 2 V | Data inputs | -75 | | | -75 | | | μА | |
| IOZH | V _{CC} = 3.6 V, | V _O = 3 V | | | | 1 | | | 1 | μΑ | |
| IOZL | V _{CC} = 3.6 V, | $V_{O} = 0.5 V$ | | | | -1 | | | -1 | μA | |
| | | | Outputs high | | 0.13 | 0.39 | | 0.13 | 0.19 | | |
| ICC | V _{CC} = 3.6 V, | $I_{O} = 0,$ | Outputs low | | 8.7 | 14 | | 8.7 | 12 | mA | |
| νυυ | | | Outputs disabled | | 0.13 | 0.39 | | 0.13 | 0.19 | | |
| ∆ICC§ | $V_{CC} = 3 V \text{ to } 3.6 V,$ Other inputs at V_{CC} | | | | | 0.3 | | | 0.2 | mA | |
| Ci | VI = 3 V or 0 | | | | 4 | | | 4 | | pF | |
| Co | $V_{O} = 3 V \text{ or } 0$ | | | | 8 | | | 8 | | pF | |

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | | | SN54LVT574 | | | | | | | |
|-----------------|---------------------------------------|------------------------------------|------------|-------------------------|-----|------------------------------------|-----|-------------------------|-----|------|
| | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 2.7 V | | UNIT |
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| fclock | Clock frequency | 0 | 150 | 0 | 150 | 0 | 150 | 0 | 150 | MHz |
| tw | Pulse duration, CLK high or low | 3.3 | | 3.3 | | 3.3 | | 3.3 | | ns |
| t _{su} | Setup time, data before $CLK\uparrow$ | 2 | | 2.4 | | 2 | | 2.4 | | ns |
| t _h | Hold time, data after CLK↑ | 0.9 | | 0.9 | | 0.3 | | 0 | | ns |



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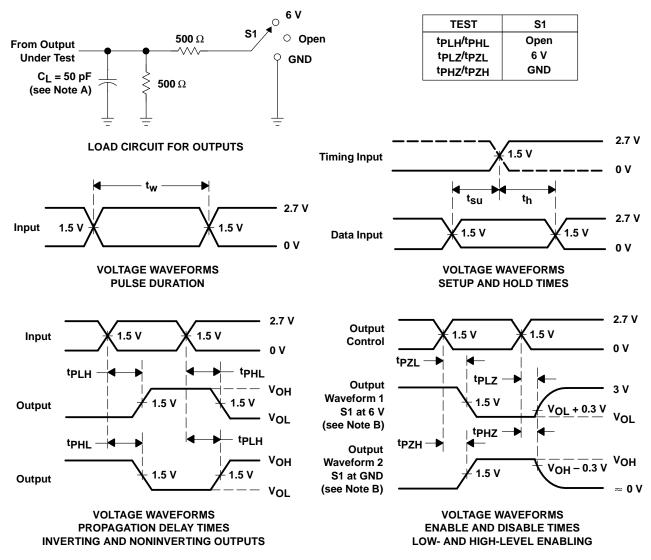
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| | | | | SN54L | VT574 | | | | | | | | | |
|------------------|-----------------|----------------|------------------------------------|-------|-------------------------|-----|------------------------------------|------|-----|-------------------------|-----|------|-----|-----|
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | | V _{CC} = 2.7 V | | UNIT | | |
| | | | MIN | MAX | MIN | MAX | MIN | түр† | MAX | MIN | MAX | | | |
| f _{max} | | | 150 | | 150 | | 150 | | | 150 | | MHz | | |
| ^t PLH | CLK | CLK | Q | 1 | 5.9 | | 6.6 | 1.7 | 3.6 | 5.4 | | 6.2 | ns | |
| ^t PHL | | ý | 1 | 6.1 | | 6.8 | 2.4 | 4.3 | 5.9 | | 6.6 | 115 | | |
| ^t PZH | OE | Q | 0.5 | 5.9 | | 7.1 | 1 | 2.9 | 4.8 | | 5.9 | ns | | |
| ^t PZL | ÛE | OE | OE | Q | 0.5 | 5.3 | | 6.4 | 1.3 | 3.4 | 5.1 | | 6.2 | 115 |
| ^t PHZ | OE | Q | 0.7 | 5.9 | | 6.6 | 1.9 | 4 | 5.5 | | 5.9 | ns | | |
| ^t PLZ | | Ŷ | 0.5 | 5.1 | | 5.1 | 1.7 | 3.2 | 4.5 | | 4.5 | 115 | | |

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns. t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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